PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE BY SECURED PARTY

CONVEYING PARTY DATA

Name	Execution Date
VENTURE LENDING & LEASING IV, INC.	03/26/2007

RECEIVING PARTY DATA

Name:	MOLECULAR IMPRINTS, INC.
Street Address:	1807-C W BRAKER LN, SUITE 100
City:	AUSTIN
State/Country:	TEXAS
Postal Code:	78758

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	10677639

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	29739.025
NAME OF SUBMITTER:	Nancy Bouch

Total Attachments: 10
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TERMINATION AND RELEASE OF
INTELLECTUAL PROPERTY SECURITYAGREEMENT

This Termination and Release of Intellectual Property Security Agreement (the "Agreement"), is made as of March 26, 2007, by VENTURE LENDING & LEASING IV, INC., a Maryland corporation ("Secured Party"), in favor of MOLECULAR IMPRINTS, INC., a Delaware corporation (together with its successors and assigns, the "Grantor").

RECITALS

A. Reference is made to a Loan and Security Agreement, dated as of September 28, 2004 (together with the Supplement to the Loan and Security Agreement, the "Loan Agreement"), by and between Grantor and Secured Party, whereby Grantor granted to Secured Party a security interest in Grantor's entire right, title and interest in all Intellectual Property of the Grantor (the "Collateral").

B. A Grant of Security Interest in Intellectual Property was filed with the United States Patent and Trademark Office, Patent Division, on January 11, 2005, at Reel/Frame 003103/0787 to evidence the security interest in patents and patent applications granted under the Loan Agreement.

C. A Grant of Security Interest in Intellectual Property was filed with the United States Patent and Trademark Office, Trademark Division, on January 11, 2005, at Reel/Frame 016133/0369 to evidence the security interest in trademarks and trademark applications granted under the Loan Agreement.

D. Debtor has provided cash collateral for its Obligations under the Loan Agreement and as a result, Grantor has requested, and Secured Party has agreed, to release its security interest in the Collateral.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, Secured Party agrees as follows:

1. Secured Party hereby expressly confirms the termination and release to Grantor of its security interest in and to all Collateral, including, but not limited to:

(a) All letters patent of, or rights corresponding thereto in, the United States or any other country, all registrations an recordings thereof, and all applications for letters patent of, or rights corresponding thereto in the United States or any other country, including, without limitation, registrations, recordings and applications in the United States Patent and Trademark Office or in any similar office or agency of the Untied States, any State thereof or any other country; all reissues, continuations, continuations-in-part or extensions thereof; all petty patents, divisionals, and patents of addition; and all patents to be issued under any such applications, including without limitation each patent and patent application set forth on Exhibit A attached hereto (collectively, the "Patents");

(b) All trademarks, trade names, corporate names, business names, trade styles, service marks, logos, other source or business identifiers, prints and labels on which any of the foregoing have appeared or appear, designs and general intangibles of like nature, all registrations and recordings thereof, and any applications in connection therewith, including, without limitation, registrations, recordings and applications in the United States Patent and Trademark Office or in any similar office or agency of the Untied States, any State thereof or any other country or political subdivision thereof, and reissues, extensions or renewals thereof and the entire goodwill of the business of Grantor connected with and symbolized by such trademarks, including without limitation each trademark and trademark application set forth on Exhibit B attached hereto (collectively, the "Trademarks").

2. Secured Party authorizes and requests that the Commissioner for Patents and Trademarks and any other government officer record this Release.

IN WITNESS WHEREOF, Secured Party has executed and delivered this Termination and Release as of the day and year first above written.

VENTURE LENDING & LEASING IV, INC.

By:__________________________
Name: Jay L. Cohan
Title: Vice President

EXHIBIT A

PATENTS AND PATENT APPLICATIONS

EXHIBIT A

MOLECULAR IMPRINTS, INC. IS THE SOLE OWNER OF THE RIGHTS IN THE FOLLOWING U.S. PATENT DOCUMENTS

	Title	Filing Date	App. No.
1)	Methods Of Manufacturing A Lithography Template	5/1/2002	10/136,188
2)	Method For Dispensing Liquids (As Amended)	7/9/2002	10/191,749
3)	Step And Repeat Imprint Lithography Process	7/11/2002	10/194,991
4)	Step And Repeat Imprint Lithography Systems	7/11/2002	10/194,414
5)	Formation Of Discontinuous Films During An Imprint Lithography Process	7/11/2002	10/194,411
6)	Method And System For Imprint Lithography Using An Electric Field	7/11/2002	10/194,410
7)	Alignment Systems For Imprint Lithography	8/1/2002	10/210,894
8)	Scatterometry Alignment For Imprint Lithography	8/1/2002	10/210,785
9)	Alignment Methods For Imprint Lithography	8/1/2002	10/210,780
10)	Method For Fabricating Bulbous-Shaped Vias	8/23/2002	10/227,105
11)	Functional Patterning Material For Imprint Lithography Processes	9/5/2002	10/235,314
12)	A Method And A Mold To Arrange Features On A Substrate To Replicate Features Having Minimal Dimensional Variability	10/4/2002	10/264,960
13)	A Method Of Forming A Layer On A Substrate To Facilitate Fabrication Of Metrology Standards	10/4/2002	10/264,926
14)	Methods Of Inspecting A Lithography Template	11/13/2002	10/293,919
15)	A Chucking System For Modulating Shapes Of Substrates	11/13/2002	10/293,224
16)	Method Of Reducing Pattern Distortions During Imprint Lithography Processes	11/13/2002	10/293,223
17)	A Method For Modulating Shapes Of Substrates	12/11/2002	10/316,963
18)	Method And System For Determining Characteristics Of Substrates Employing Fluid Geometries	12/12/2002	10/318,365
19)	Composition And Method To Form A Release Layer	2/27/2003	10/375,832
20)	Method To Reduce Adhesion Between A Polymerizable Layer And A Substrate Employing A Fluorine-Containing Layer	2/27/2003	10/375,817
21)	Positive Tone Bi-Layer Imprint Lithography Method	3/25/2003	10/396,615
22)	A Method Of Forming Stepped Structures Employing Imprint Lithography	4/25/2003	10/423,642

Title	Filing Date	App. No.
23) Method, System And Holder For Transferring Templates During Imprint Lithography Processes	5/14/2003	10/438,224
24) Assembly And Method For Transferring Imprint Lithography Templates	5/14/2003	10/437,476
25) High-Resolution Overlay Alignment Systems For Imprint Lithography	5/27/2003	10/445,863
26) A Conforming Template For Patterning Liquids Disposed On Substrates	7/7/2003	10/614,716
27) Systems For Magnification And Distortion Correction For Imprint Lithography Processes	7/9/2003	10/616,294
28) Capillary Imprinting Technique	8/21/2003	10/645,306
29) Imprint Lithography Template Having Opaque Alignment Marks	9/25/2003	10/670,980
30) Formation Of Conductive Templates Employing Indium Tin Oxide	11/12/2003	10/706,537
31) Dispense Geometry To Achieve High-Speed Filling And Throughput	11/14/2003	10/714,088
32) Magnification Correction Employing Out-Of-Plane Distortion Of A Substrate	12/12/2003	10/735,110
33) Thermal Processing System For Imprint Lithography	1/15/2004	10/758,384
34) A Method To Improve The Flow Rate Of Imprinting Material	1/15/2004	10/757,778
35) Method For Concurrently Employing Differing Materials To Form A Layer On A Substrate	1/20/2004	10/760,821
36) Materials And Methods For Imprint Lithography	1/23/2004	10/763,885
37) Method And System To Measure Characteristics Of A Film Disposed On A Substrate	2/19/2004	10/782,187
38) Composition For An Etching Mask Comprising A Silicon-Containing Material	2/27/2004	10/789,319
39) Full-Wafer Or Large Area Imprinting With Multiple Separated Sub-Fields For High Throughput Lithography	2/27/2004	10/788,700
40) A Method Of Inspecting Substrates Employing Signal Superimposition	4/19/2004	10/827,119
41) Method Of Forming A Deep-Featured Template Employed In Imprint Lithography	4/19/2004	10/827,118
42) Compliant Hard Template For UV Imprinting	4/27/2004	10/833,240
43) Method Of Patterning A Conductive Layer On A Substrate	5/11/2004	10/843,194
44) A Method Of Forming A Recessed Structure Employing A Reverse Tone Process	5/21/2004	10/850,876

	Title	Filing Date	App. No.
45)	A Method Of Dispensing A Fluid On A Substrate	6/1/2004	10/858,566
46)	A Compliant Device For Nano-Scale Manufacturing	6/1/2004	10/858,179
47)	Method And System To Control Movement Of A Body For Nano-Scale Manufacturing	6/1/2004	10/858,100
48)	System For Determining Characteristics Of Substrates Employing Fluid Geometries	6/8/2004	10/863,800
49)	A Chucking System For Modulating Shapes Of Substrates	6/9/2004	10/864,591
50)	System For Dispensing Liquids	6/15/2004	10/868,683
51)	Imprint Alignment Method, System And Template	7/20/2004	10/895,214
52)	Imprinting Of Displays	7/23/2004	10/897,734
53)	Moat System For An Imprint Lithography Template	8/13/2004	10/917,761
54)	A Method Of Planarizing A Semiconductor Substrate	8/13/2004	10/917,563
55)	Method To Provide A Layer With Uniform Etch Characteristics	8/16/2004	10/919,224
56)	Composition To Provide A Layer With Uniform Etch Characteristics	8/16/2004	10/919,062
57)	Apparatus For Imprint Lithography Using An Electric Field	8/20/2004	10/923,629
58)	System For Determining Characteristics Of Substrates Employing Fluid Geometries	8/20/2004	10/923,628

MOLECULAR IMPRINTS SHARES THE OWNERSHIP OF THE RIGHTS IN THE FOLLOWING U.S. PATENT DOCUMENTS WITH ONE OTHER ORGANIZATION

1)	Low Viscosity High Resolution Patterning Material	6/24/2002	10/178,947
2)	Method To Reduce Adhesion Between A Conformable Region And A Pattern Of A Mold	6/17/2003	10/463,396
3)	Single Phase Fluid Imprint Lithography Method	10/2/2003	10/677,639
4)	Applying Imprinting Material To Substrates Employing Electromagnetic Fields	10/16/2003	10/687,562
5)	Low Surface Energy Templates	10/16/2003	10/687,519
6)	Methods For Fabricating Patterned Features Utilizing Imprint Lithography	10/27/2003	10/694,284
7)	Materials For Imprint Lithography	2/23/2004	10/784,911
8)	An Apparatus For Creating A Turbulent Flow Of Fluid Between A Mold And A Substrate	7/23/2004	10/898,037
9)	Method For Creating A Turbulent Flow Of Fluid Between A Mold And A Substrate	7/23/2004	10/898,034

MOLECULAR IMPRINTS, INC. IS THE SOLE OWNER OF THE RIGHTS IN THE FOLLOWING INTERNATIONAL AND FOREIGN PATENT DOCUMENTS

1)	A Chucking System and Method for Modulating Shapes of Substrates	PCT	Nov 12, 2003	PCT/US03/36012
2)	A Chucking System and Method for Modulating Shapes of Substrates	MY	Nov 12, 2003	PI 20034332
3)	A Chucking System and Method for Modulating Shapes of Substrates	TW	Nov 12, 2003	92131719
4)	A Chucking System and Method for Modulating Shapes of Substrates	DE	May 17, 2004	203 20 446.8
5)	A Method and a Mold to Arrange Features on a Substrate to Replicate Features Having Minimal Dimensional Variability	PCT	Sep 18, 2003	PCT/US03/29061
6)	A Method and a Mold to Arrange Features on a Substrate to Replicate Features Having Minimal Dimensional Variability	MY	Sep 25, 2003	PI 20033654
7)	A Method and a Mold to Arrange Features on a Substrate to Replicate Features Having Minimal Dimensional Variability	TW	Sep 26, 2003	92126696
8)	A Method of Forming Stepped Structures Employing Imprint Lithography	PCT	Apr 21, 2004	PCT/US04/12313
9)	A Method of Forming Stepped Structures Employing Imprint Lithography	MY	Apr 23, 2004	PI 20041496
10)	A Method of Forming Stepped Structures Employing Imprint Lithography	TW	Apr 23, 2004	93111426
11)	Capillary Imprinting Technique	PCT	Aug 13, 2004	PCT/US04/26337
12)	Capillary Imprinting Technique	PCT	Aug 13, 2004	PCT/US04/26337
13)	Capillary Imprinting Technique	MY	Aug 17, 2004	
14)	Capillary Imprinting Technique	TW	Aug 20, 2004	93125173
15)	Formation of Discontinuous Films During an Imprint Lithography Process	PCT	Jul 10, 2003	PCT/US03/21556
16)	Formation of Discontinuous Films During an Imprint Lithography Process	MY	Jul 7, 2003	PI 20032546
17)	Formation of Discontinuous Films During an Imprint Lithography Process	TW	Jul 10, 2003	92118881
18)	Magnification Correction Employing Out-Of-Plane Distortion of a Substrate	PCT	Dec 12, 2003	PCT/US03/39448
19)	Magnification Correction Employing Out-Of-Plane Distortion of a Substrate	MY	Dec 12, 2003	PI 20034775
20)	Magnification Correction Employing Out-Of-Plane Distortion of a Substrate	TW	Dec 12, 2003	92135221
21)	Method And System For Determining Characteristics Of Substrates Employing Fluid Geometries	PCT	Dec 12, 2003	PCT/US03/39449
22)	Method and System for Imprint Lithography Using an Electric Field	MY	Jul 7, 2003	PI 20032545
23)	Method and System for Imprint Lithography Using an Electric Field	TW	Jul 10, 2003	92118873

24)	Method, System, Holder and Assembly for Transferring Templates during Imprint Lithography Processes	PCT	May 11, 2004	PCT/US04/14720
25)	Positive Tone Bi-Layer Imprint Lithography Method and Compositions Therefor	PCT	Mar 24, 2004	PCT/US04/08920
26)	Positive Tone Bi-Layer Imprint Lithography Method and Compositions Therefor	MY	Mar 25, 2004	PI 20041060
27)	Positive Tone Bi-Layer Imprint Lithography Method and Compositions Therefor	TW	Mar 24, 2004	93107963
28)	Scatterometry Alignment for Imprint Lithography	PCT	Jul 31, 2003	PCT/US03/23948
29)	Scatterometry Alignment for Imprint Lithography	MY	Jul 30, 2003	PI 20032888
30)	Scatterometry Alignment for Imprint Lithography	TW	Jul 31, 2003	92120993
31)	Step and Repeat Imprint Lithography Process	MY	Jul 7, 2003	PI 20032541
32)	Step and Repeat Imprint Lithography Process	TW	Jul 10, 2003	92118862
33)	Step and Repeat Imprint Lithography Systems	MY	Jul 7, 2003	PI-20032540
34)	Step and Repeat Imprint Lithography Systems	TW	Jul 10, 2003	92118883
35)	System and Method for Dispensing Liquids	PCT	Jun 19, 2003	PCT/US03/19258
36)	System and Method for Dispensing Liquids	MY	Jun 27, 2003	PI-20032433
37)	System and Method for Dispensing Liquids	TW	Jun 30, 2003	92117835
38)	Systems for Magnification and Distortion Correction for Imprint Lithography Processes	PCT	Jul 9, 2004	PCT/US04/22454
39)	Systems for Magnification and Distortion Correction for Imprint Lithography Processes	MY	Jul 9, 2004	PI 20042743
40)	Systems for Magnification and Distortion Correction for Imprint Lithography Processes	TW	Jul 8, 2004	93120450

MOLECULAR IMPRINTS SHARES THE OWNERSHIP OF THE RIGHTS IN THE FOLLOWING INTERNATIONAL AND FOREIGN DOCUMENTS WITH ONE OTHER ORGANIZATION

1)	Method to Reduce Adhesion Between a Conformable Region and a Pattern of a Mold	PCT	6/10/2004	PCT/US2004/018857
2)	Method to Reduce Adhesion Between a Conformable Region and a Pattern of a Mold	MY	6/15/2004	PI 20042293
3)	Method to Reduce Adhesion Between a Conformable Region and a Pattern of a Mold	TW	6/16/2004	93117326

EXHIBIT B

TRADEMARK AND TRADEMARK APPLICATIONS

THIS EXHIBIT INTENTIONALLY OMITTED